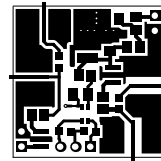
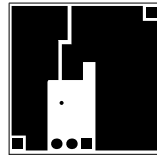


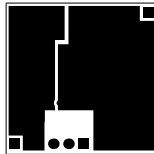
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Top Solder Mask	GENERATED : 10/10/2013 4:47:06 PM	TEXAS INSTRUMENTS	



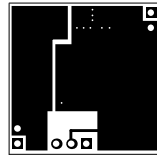
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Top Layer	GENERATED : 10/10/2013 4:47:06 PM	TEXAS INSTRUMENTS	



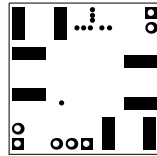
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Mid Layer 1	GENERATED : 10/10/2013 4:47:06 PM	TEXAS INSTRUMENTS	



	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Mid Layer 2	GENERATED : 10/10/2013 4:47:07 PM	TEXAS INSTRUMENTS	



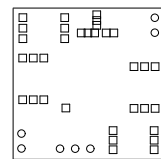
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Bottom Layer	GENERATED : 10/10/2013 4:47:07 PM	TEXAS INSTRUMENTS	



	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Bottom Solder Mask	GENERATED : 10/10/2013 4:47:08 PM	TEXAS INSTRUMENTS	



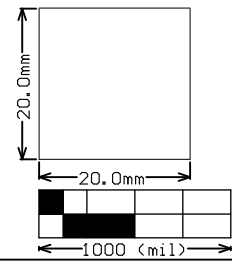
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Bottom Overlay	GENERATED : 10/10/2013 4:47:08 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	33	10mil (0.254mm)	PTH	Round
○	7	35mil (0.889mm)	PTH	Round
	40 Total			

Drill Table

	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Drill Drawing	GENERATED : 10/10/2013 4:47:08 PM		TEXAS INSTRUMENTS



	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Board Dimensions	GENERATED : 10/10/2013 4:47:09 PM	TEXAS INSTRUMENTS	

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